NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This is a Pb-free solder ball design.
NOTES: (continued)

4. Final dimensions may vary due to manufacturing tolerance considerations and also routing constraints. See Texas Instruments Literature No. SSZA002 (www.ti.com/lit/ssza002).
5. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release.
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